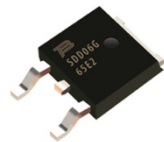


MATERIAL DECLARATION SHEET



Material Number	BSDD06G65E2 TO252			
Product Line	Semiconductor			
Compliance Date	2023-3-22			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	0.7	Silicon Carbide (SiC)	409-21-2	100	0.08	0.08
2	Die Attach	Silver	0.08	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.01	0.17
			1.42	Silver (Ag)	7440-22-4	95	0.16	
3	Lead Frame	Copper alloy	0.1	Phosphorous (P)	7723-14-0	0.03	0.01	38.44
			0.1	Nickel (Ni)	7440-02-0	0.03	0.01	
			0.35	Iron (Fe)	7439-89-6	0.1	0.04	
			347.84	Copper (Cu)	7440-50-8	99.84	38.38	
4	Mold Compound	Resin	20.18	Phenol Formaldehyde resin (generic)	9003-35-4	3.8	2.23	58.62
			31.87	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6	3.52	
			478.04	Silica fused	60676-86-0	90	52.75	
			1.06	Carbon black	1333-86-4	0.2	0.12	
5	Post-plating	Pure metal	24	Tin (Sn)	7440-31-5	100	2.65	2.65
6	Wire	Pure metal	0.38	Aluminium (Al)	7429-90-5	100	0.04	0.04
Total weight			906.12 mg					

This Document was updated on: 2023/3/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which is exempt from the requirements